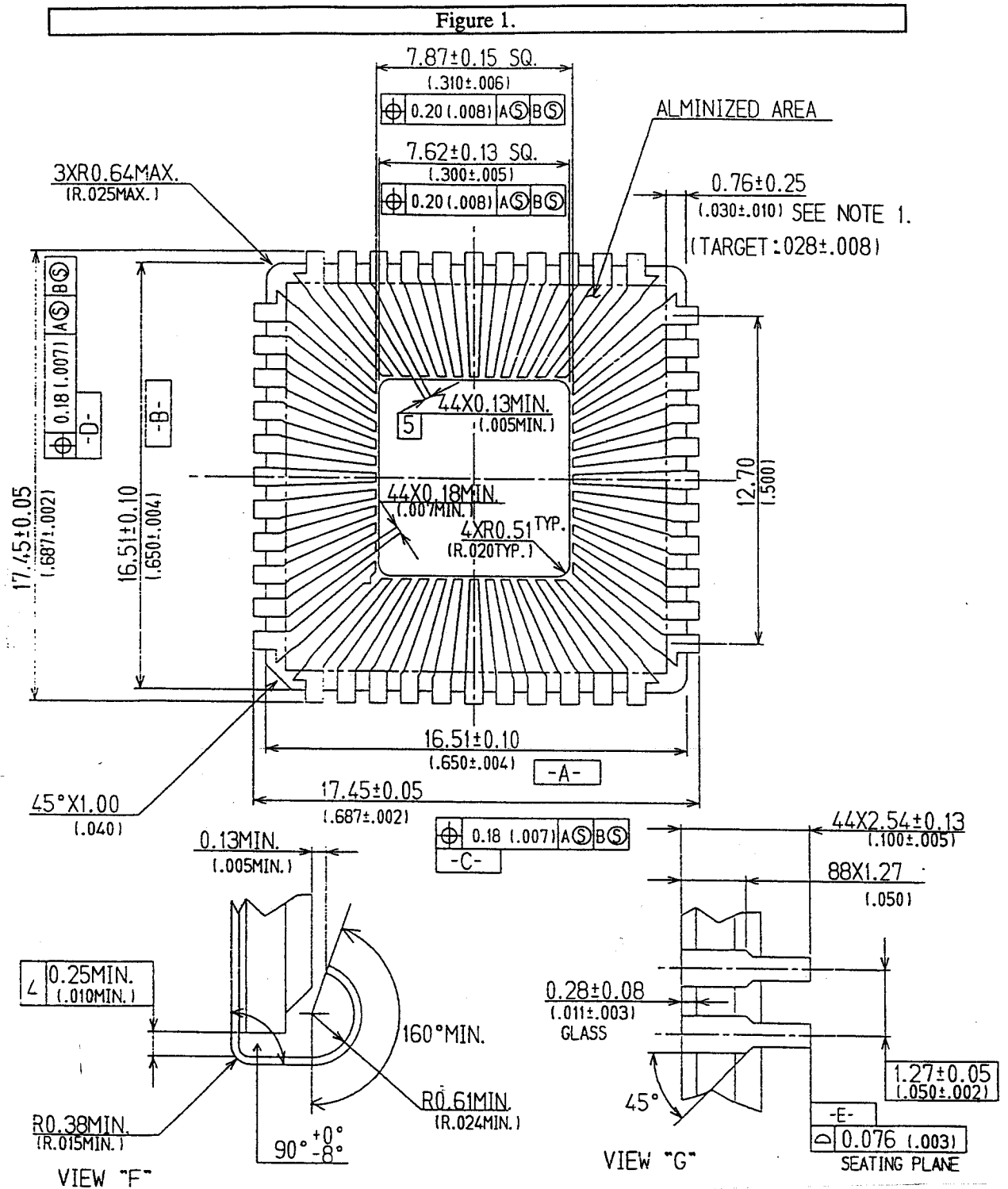


# SSM P/N CQJ04410

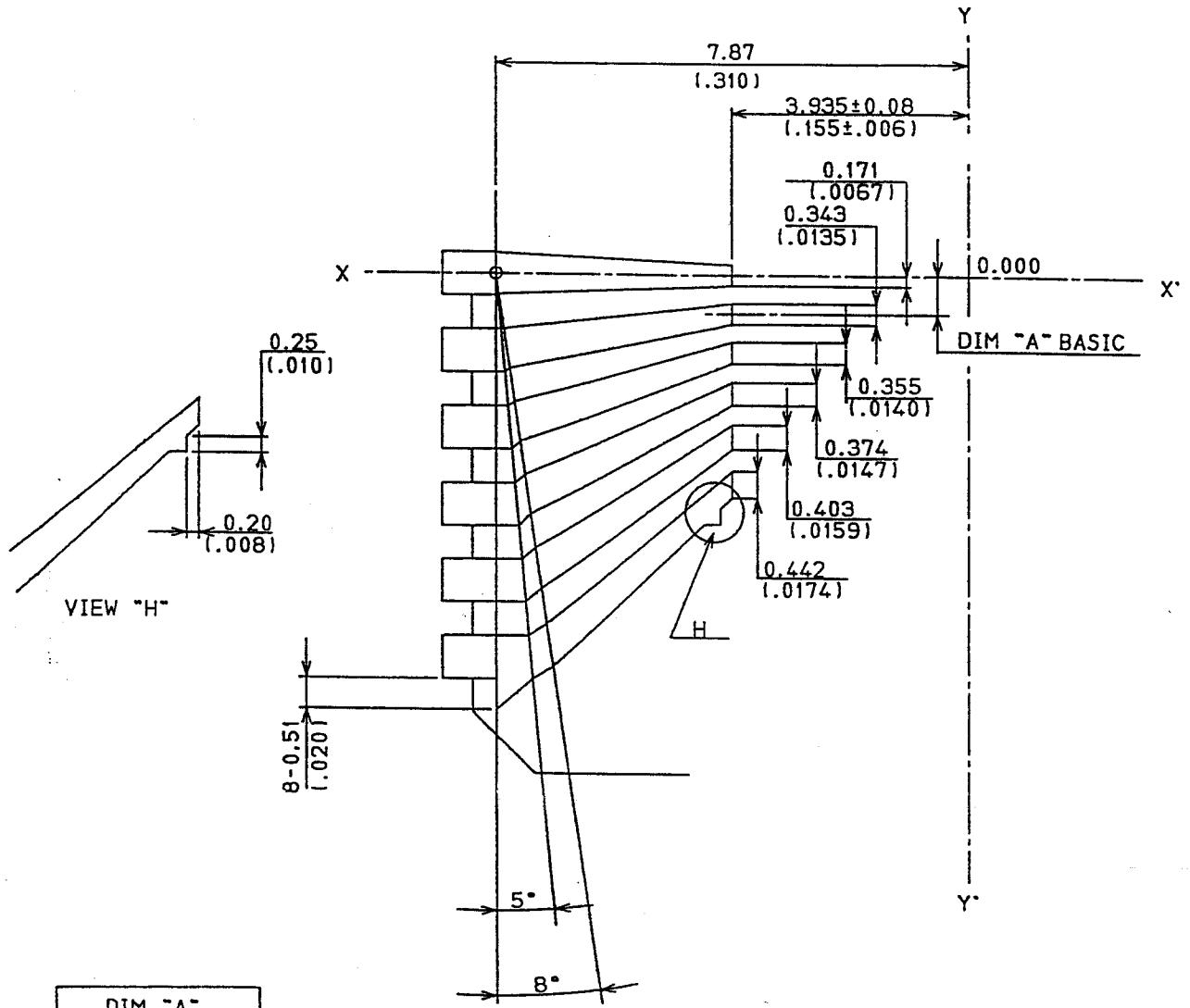
BASE, 44 LD J-CQ, .300 SQ BARE CAVITY



# SSM P/N CQJ04410

BASE, 44 LD J-CQ, .300 SQ BARE CAVITY

Figure 1. (con't)



DIM "A" BASIC	
0.633	(.025)
1.277	(.050)
1.950	(.077)
2.669	(.105)
3.450	(.136)

TYP ALL QUAD.

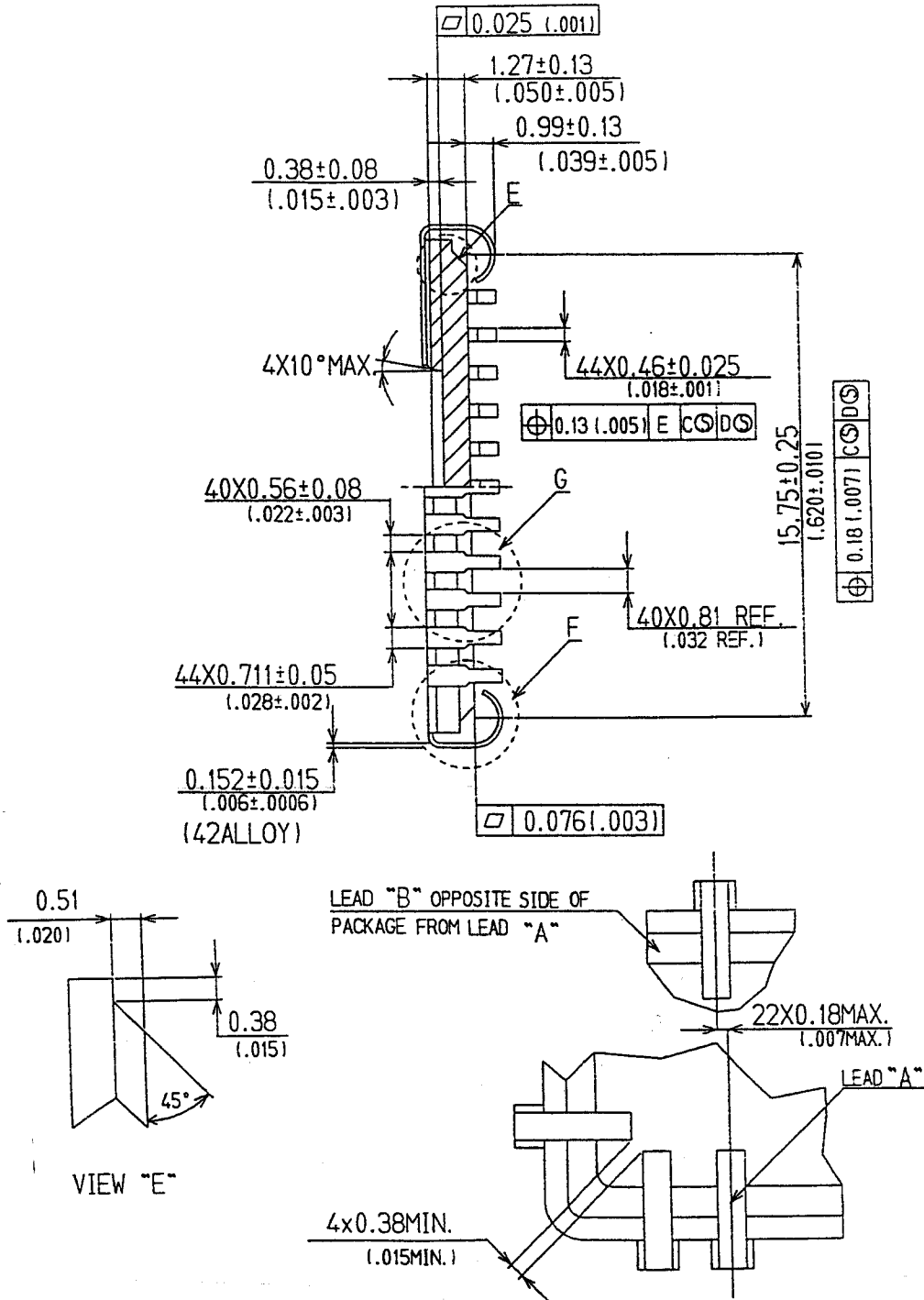
LEAD TIP DETAIL



# SSM P/N CQJ04410

BASE, 44 LD J-CQ, .300 SQ BARE CAVITY

Figure 1. (con't)



# SSM P/N CQJ04410

BASE, 44 LD J-CQ, .300 SQ BARE CAVITY

## NOTES:

1. MATERIALS
  - o CERAMIC TO BE OPAQUE 90-94%  $AL_2O_3$ .
  - o SOLDER GLASS TO BE 7583. MAX PULLBACK TO BE 0.25 (0.010) FROM CERAMIC EDGE.
  - o DIE ATTACH AREA TO BE BARE.
  - o LEAD FRAME TO BE ALLOY 42. TYPE 8 MIL 38510 PARAGRAPH 3.5.6.1 WITH ALUMINUM BOND PADS. 100 MICROINCH MINIMUM THICKNESS AND  $0.76 \pm 0.25$  ( $0.030 \pm 0.010$ ) FROM SUBSTRATE EDGE.
2. THERE WILL BE NO UNSUPPORTED BOND PADS GREATER THAN 0.25 (0.010).
3. ADJACENT BOND PADS MUST BE CO-PLANAR WITHIN 0.15 (0.006). TOTAL CO-PLANARITY NO GREATER THAN 0.25 (0.010).
4. THERE WILL BE NO NICKS, CUTS OR GLASS IN THE BEND RADIUS.
5. MINIMUM INTERNAL METAL SEPARATION OTHER THAN BOND FINGERS TO BE 0.13 (0.005).

